

本机采用半导体端面泵浦激光器，经过三倍频产生 355nm 紫外激光。光电转化率高，设备稳定性好，振镜式高精度打标头，效果精细，355nm 输出波长，减少对加工工件的热影响。

This machine uses a semiconductor end-pumped laser to generate 355nm ultraviolet laser after triple frequency. It boasts high conversion rate between laser and electricity. High stability and it adopts galvo marking head with super precision. Output wavelength is 355nm. It boasts small heat affection.

- 效率高，打标效果好，整机小巧，运输便捷。
- 电光转换效率高，激光器脉宽窄，峰值功率高。
- 热影响区域小，适合高精度加工的划线及各种复杂图案打标，速度快，整机稳定性好。
- High efficiency and good marking effect, small volume, and the transportation is convenient;
- High electro-optic conversion efficiency, narrow laser pulse width, high peak power.
- Small heat affected area, suitable for high-precision machining of scribing and various complex pattern marking fast, good stability.



广泛应用于食品、药品、化妆品、电线等高分子材料的包装瓶（盒）表面打标，打微孔（孔径  $D \leq 10\mu\text{m}$ ）柔性 PCB 板、LCD、TFT 打标、划片切割等金属或非金属镀层去除硅晶圆片微孔、盲孔加工。

Widely used in marking on packing materials of food, medicines, cosmetics and wire, drilling tiny hole (hole diameter  $D \leq 10\mu\text{m}$ ) Flexible PCB, LCD, TFT marking and slicing. Metallic and non metallic materials thin film removal. Silicon wafer tiny hole and dead hole processing.

适用于玻璃、高分子材料等物体表面打标，微孔加工。

It is suitable for the surface marking of glass, polymer materials, etc., micro-hole processing.

性能 / 型号	Performance/model	SK-UV3	SK-UV5	SK-UV10
激光器功率	Laser power	3W	5W	10W
激光波长	Wavelength	355nm		
冷却方式	Cooling	风冷 / 水冷 Air/Water	水冷 Water	
标记范围	Marking scope	100*100/150*150/200*200mm 可定制 (Customizable)		
重复精度	Repeat accuracy	<2 $\mu\text{rad}$		
光束质量 $M^2$	Beam quality $M^2$	<1.2		
供电电源	Power supply	AC220V $\pm$ 10%/1PH/50Hz		
机器尺寸 (长 * 宽 * 高)	Machine size (L*W*H)	950*675*1500mm		
机器重量	Machine weight	150Kg		